

ABSTRACT OF THE DISCLOSURE**TITLE OF INVENTION: ELECTRONIC COMPONENTS TO BE MOUNTED
ON A CIRCUIT BOARD AND METHOD OF
MANUFACTURING THE SAME**

In an electronic component to be soldered on a printed board, it is an object of the invention to present an electronic component to be mounted on a printed board excellent in solderability, having same contact reliability as in prior art. For example, in a push switch, contact terminals 10, 12 connected to a printed board are plated with silver (or silver-alloy) low in contact resistance on the side of the surface contacting with fixed contacts 11A; 11B, 13, and the surface of the opposite side of the silver (or silver-alloy) plated surface is treated with solder of excellent solderability or tin plating. In this constitution, while maintaining the contact reliability of the switch contact parts, deterioration of solder wettability of the terminal is prevented, so that the connection terminals of electronic component can be connected securely by soldering to the printed board.

Selected drawing: Fig. 1